

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claims 1-17 (Canceled)

Claim 18 (New): A method of electrically connecting an electronic device to a substrate, said method comprising:

    passing free ends of a plurality of elongate spring contacts attached to said electronic device through openings in a plurality of conductive recesses at a surface of said substrate; and  
    pressing said free ends against bottom portions of said conductive recesses located within said substrate.

Claim 19 (New): The method of claim 18, wherein said electronic device comprises a semiconductor device.

Claim 20 (New): The method of claim 18, wherein each of said recesses is V shaped.

Claim 21 (New): The method of claim 18, wherein each of said recesses is U shaped.

Claim 22 (New): The method of claim 18, wherein each of said recesses is trapezoidal shaped.